



# FFPF10H60S Hyperfast 2 Rectifier

## Features

- High Speed Switching (  $t_{rr}=25\text{ns(Typ.)}$  @  $I_F=10\text{A}$  )
- High Reverse Voltage and High Reliability
- Avalanche Energy Rated
- Low Forward Voltage(  $V_F=2.1\text{V(Typ.)}$  @  $I_F=10\text{A}$  )

## Applications

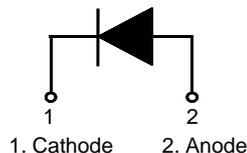
- General Purpose
- Switching Mode Power Supply
- Free-wheeling diode for motor application
- Power switching circuits

## 10A, 600V Hyperfast 2 Rectifier

The FFPF10H60S is hyperfast2 rectifier ( $t_{rr}=25\text{ns(Typ.)}$  @  $I_F=10\text{A}$ ). It has half the recovery time of ultrafast rectifier and is silicon nitride passivated ion-implanted epitaxial planar construction.

This device is intended for use as freewheeling/clamping rectifiers in a variety of switching power supplies and other power switching applications. Its low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors.

## Pin Assignments



## Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Peak Repetitive Reverse Voltage	600	V
$V_{RWM}$	Working Peak Reverse Voltage	600	V
$V_R$	DC Blocking Voltage	600	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 85^\circ\text{C}$	10	A
$I_{FSM}$	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	100	A
$T_J, T_{STG}$	Operating Junction and Storage Temperature	- 65 to +150	$^\circ\text{C}$

## Thermal Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	3.4	$^\circ\text{C/W}$

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
F10H60S	FFPF10H60STU	TO-220F	-	-	50

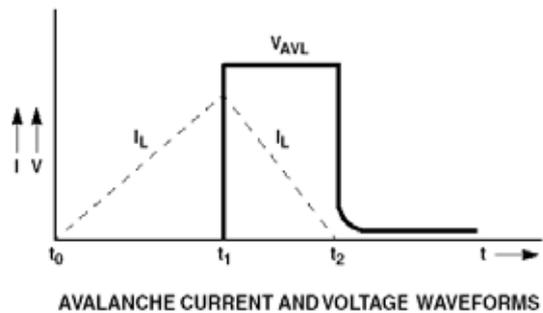
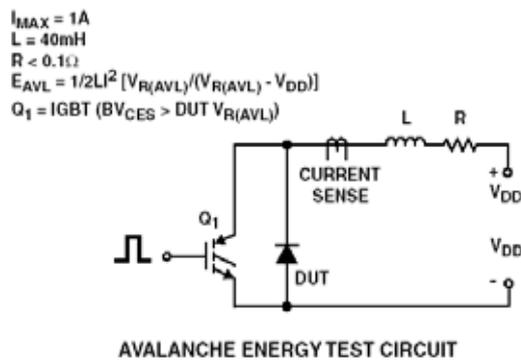
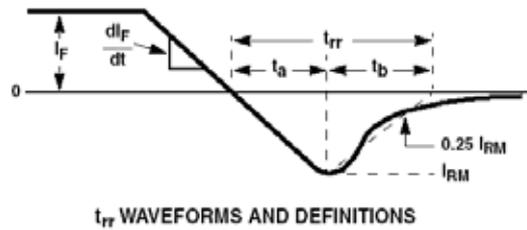
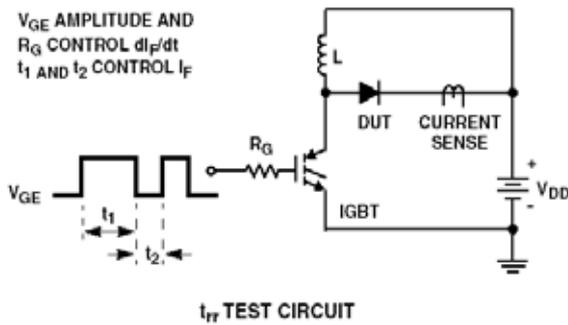
### Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

Parameter	Conditions	Min.	Typ.	Max	Units	
V <sub>FM</sub> <sup>1</sup>	I <sub>F</sub> = 10A	T <sub>C</sub> = 25 °C	-	2.1	2.5	V
	I <sub>F</sub> = 10A	T <sub>C</sub> = 125 °C	-	-	2.2	V
I <sub>RM</sub> <sup>1</sup>	V <sub>R</sub> = 600V	T <sub>C</sub> = 25 °C	-	-	1	mA
	V <sub>R</sub> = 600V	T <sub>C</sub> = 125 °C	-	-	2	mA
t <sub>rr</sub>	I <sub>F</sub> = 1A, di/dt = 100A/μs, V <sub>CC</sub> = 30V	T <sub>C</sub> = 25 °C	-	-	35	ns
	I <sub>F</sub> = 10A, di/dt = 50A/μs, V <sub>CC</sub> = 390V	T <sub>C</sub> = 25 °C	-	25	40	ns
	I <sub>F</sub> = 10A, di/dt = 200A/μs, V <sub>CC</sub> = 390V	T <sub>C</sub> = 25 °C	-	21	-	ns
t <sub>a</sub>	I <sub>F</sub> = 10A, di/dt = 50A/μs, V <sub>CC</sub> = 390V	T <sub>C</sub> = 25 °C	-	15	-	ns
t <sub>b</sub>		T <sub>C</sub> = 25 °C	-	10	-	ns
Q <sub>rr</sub>		T <sub>C</sub> = 25 °C	-	9.0	-	nC
W <sub>AVL</sub>	Avalanche Energy (L = 40mH)		20	-	-	mJ

**Notes:**

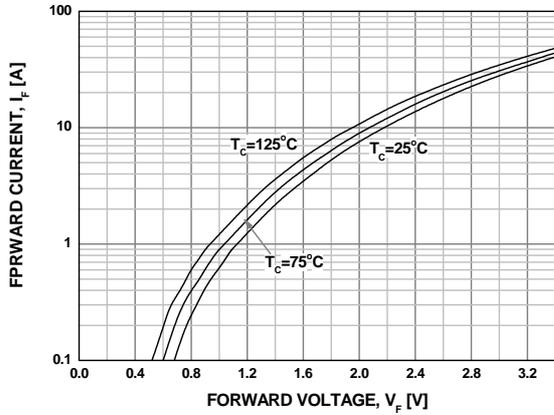
1. Pulse : Test Pulse width = 300μs, Duty Cycle = 2%

### Test Circuit and Waveforms

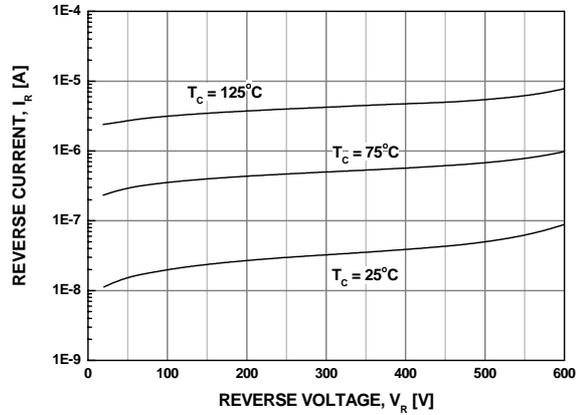


**Typical Performance Characteristics**  $T_c = 25^\circ\text{C}$  unless otherwise noted

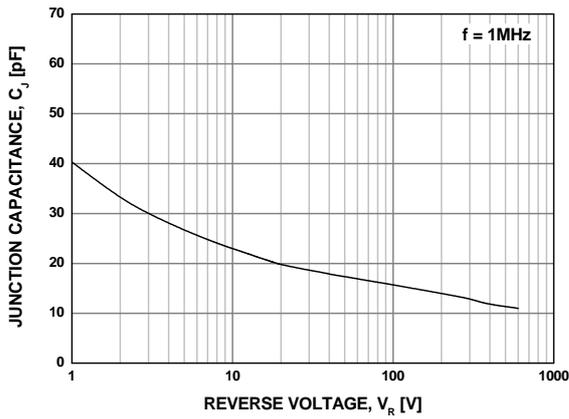
**Figure 1. Typical Forward Voltage Drop**



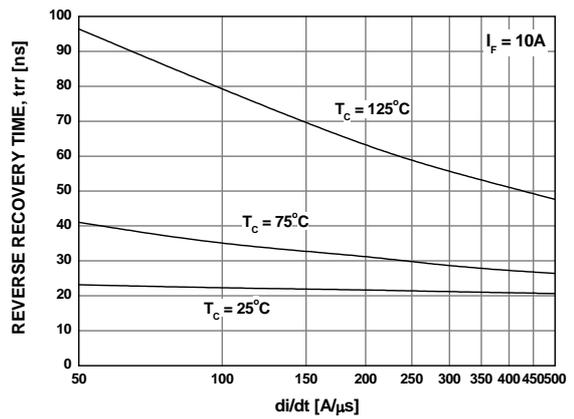
**Figure 2. Typical Reverse Current**



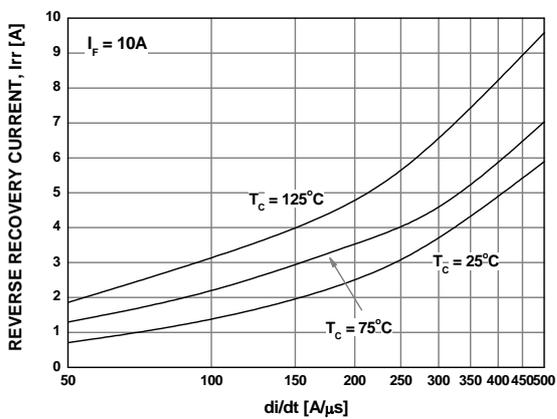
**Figure 3. Typical Junction Capacitance**



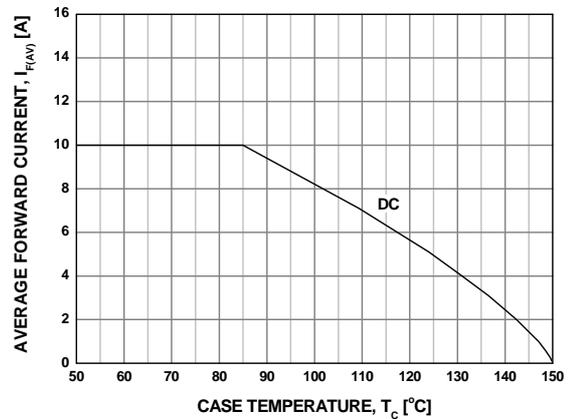
**Figure 4. Typical Reverse Recovery Time**



**Figure 5. Typical Reverse Recovery Current**

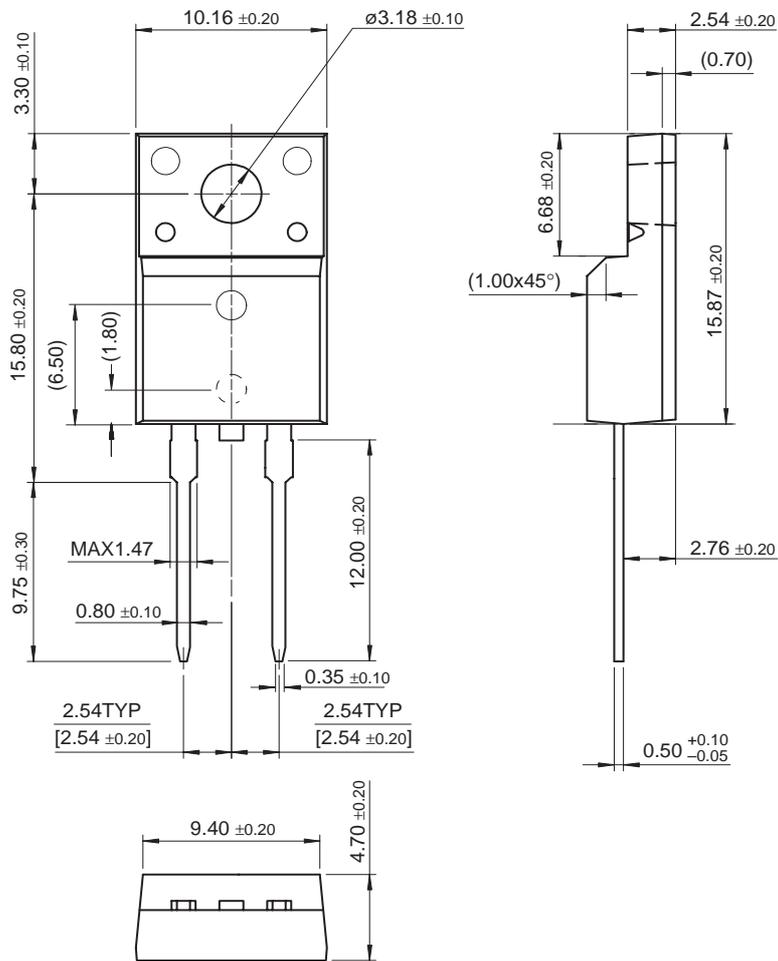


**Figure 6. Forward Current Deration Curve**



Mechanical Dimensions

TO-220F 2L



Dimensions in Millimeters



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FPST <sup>™</sup>	POP <sup>™</sup>	SuperSOT <sup>™</sup> -6	
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